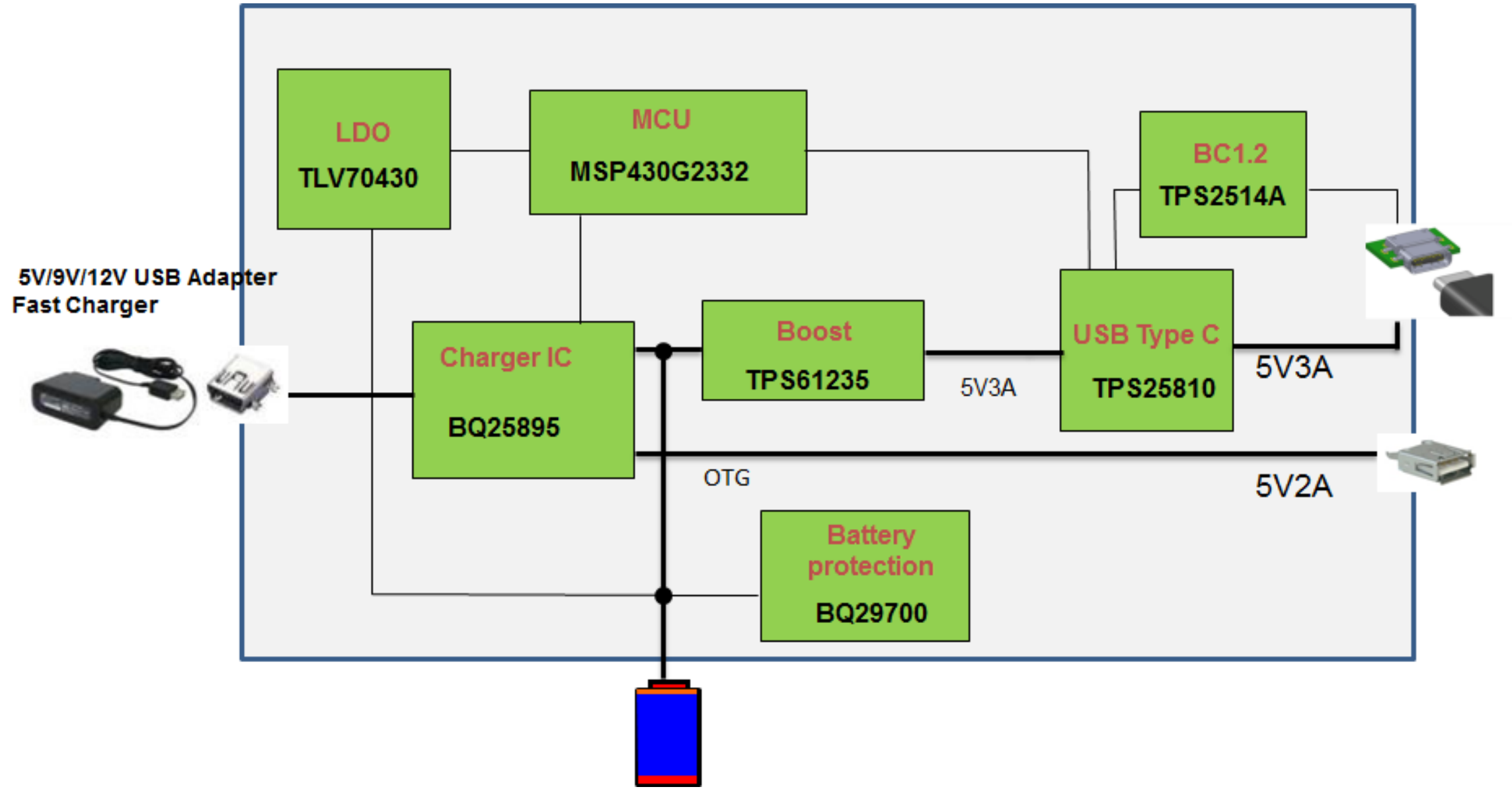
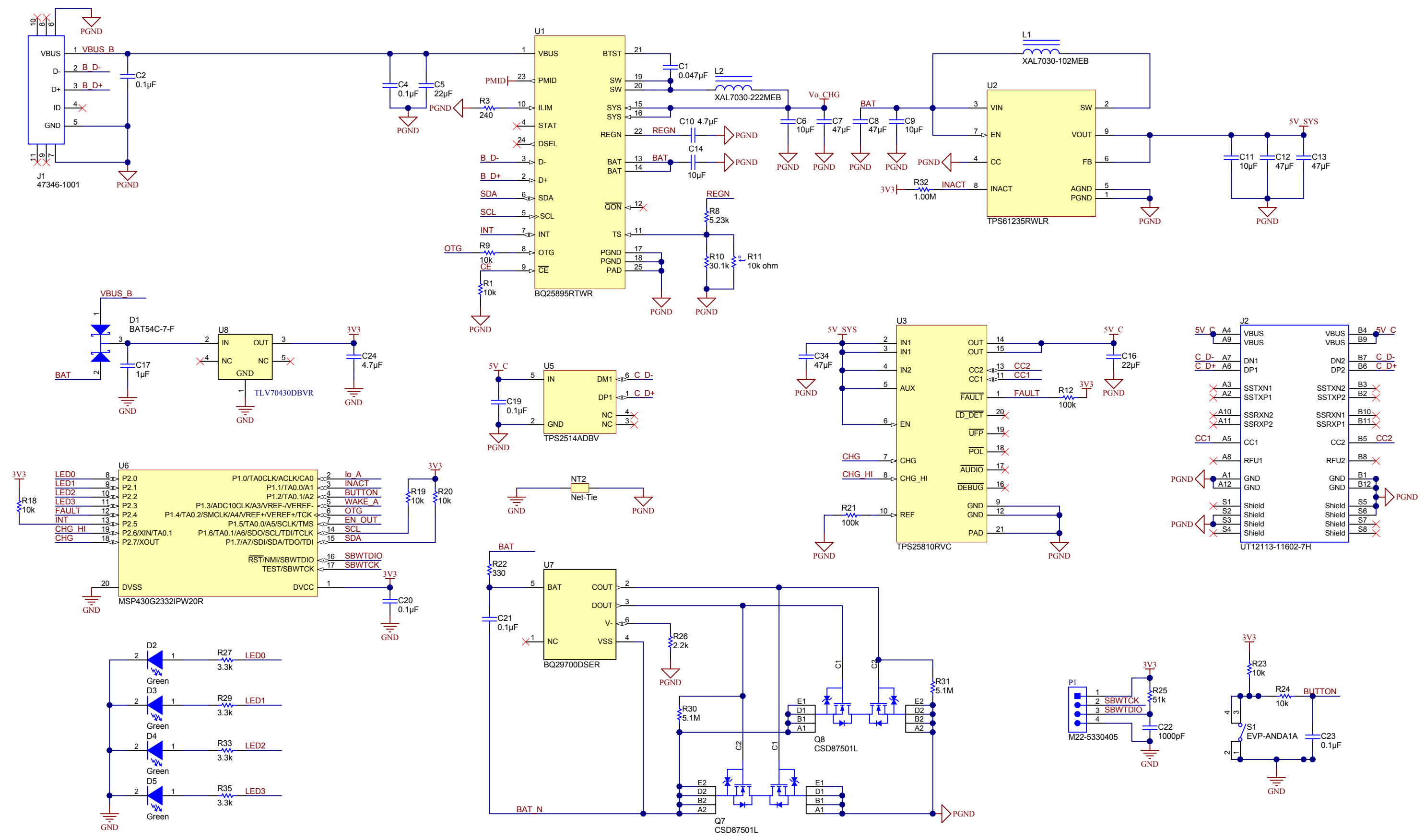


Revision History	
Revision	Notes
1.0	For Public Release



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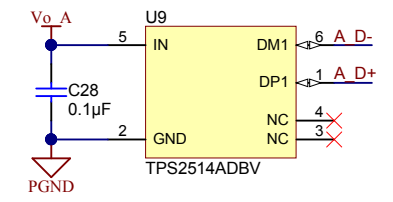
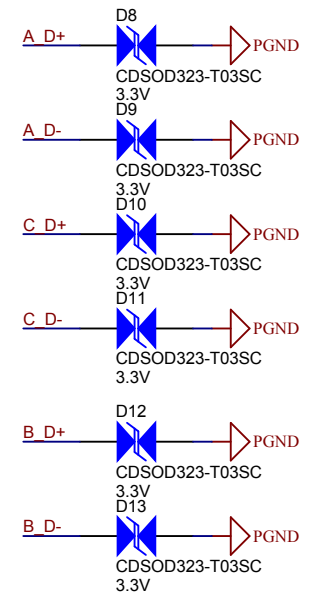
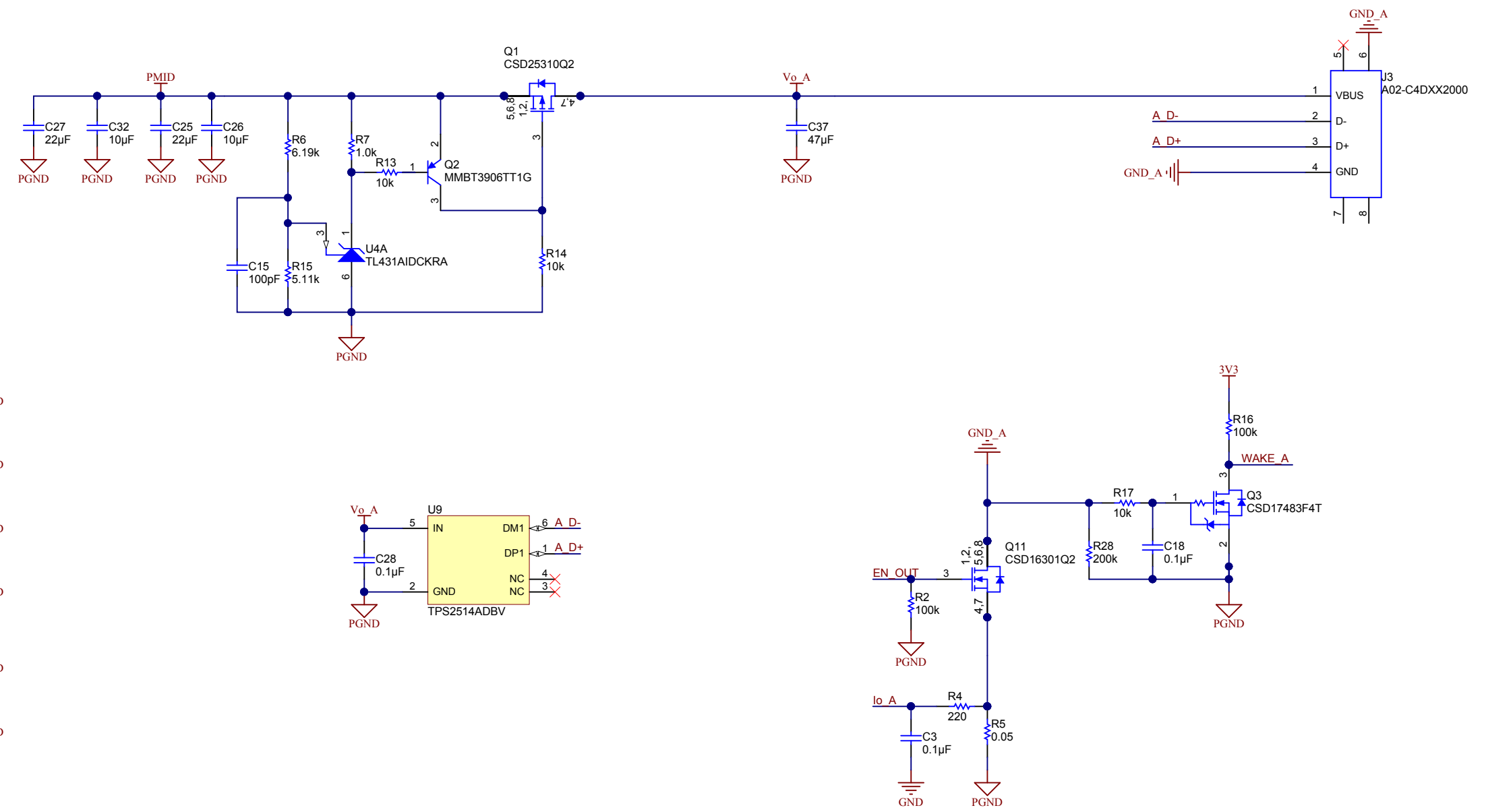
Orderable: N/A	Designed for: Public Release	Mod. Date: 11/3/2015	 <a href="http://www.ti.com">http://www.ti.com</a>
TID #: PM11536	Project Title: USB-C DFP + 5V2A Power Bank With Input Fast Ch	Sheet: 1 of 3	
Number: PMP11536	Rev: 1.0	Assembly Variant: 001	Size: B
SVN Rev: Version control disabled	Drawn By: Yingyang Ou	File: PMP11536_Cover.SchDoc	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>



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TID #: PM11536	Project Title: USB-C DFP + 5V2A Power Bank With Input Fast Ch	
Number: PMP11536	Rev: 1.0	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By:	File: PMP11536_CHG and C Port.SchDoc	Size: B
Engineer: Yingyang Ou	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	





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PCB  
LOGO  
Pb-Free Symbol

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ1  
**Assembly Note**  
 These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2  
**Assembly Note**  
 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3  
**Assembly Note**  
 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Orderable: N/A	Designed for: Public Release	Mod. Date: 10/30/2015
TID #: PM11536	Project Title: USB-C DFP + 5V2A Power Bank With Input Fast Ch	
Number: PMP11536	Rev: 1.0	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 3
Drawn By:	File: PMP11536_Hardware.SchDoc	Size: B
Engineer: Yingyang Ou	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	



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